



Material Content Data Sheet



Sales Product Name		IPG20N06S2L-35		Issued		1. August 2018		
MA#		MA001668852						
Package		PG-TDSON-8-4		Weight*		97.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.173	3.25	3.25	32537	32537
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		138	
	non noble metal	iron	7439-89-6	0.045	0.05		458	
	non noble metal	copper	7440-50-8	44.654	45.79	45.85	457854	458450
	non noble metal	aluminium	7429-90-5	0.762	0.78	0.78	7811	7811
wire	non noble metal	aluminium	7429-90-5	0.762	0.78	0.78	7811	7811
encapsulation	organic material	carbon black	1333-86-4	0.088	0.09		903	
	plastics	epoxy resin	-	6.255	6.41		64133	
	inorganic material	silicondioxide	60676-86-0	37.705	38.66	45.16	386603	451639
leadfinish	non noble metal	tin	7440-31-5	1.308	1.34	1.34	13408	13408
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	492	493
solder	non noble metal	tin	7440-31-5	0.070	0.07		713	
	noble metal	silver	7440-22-4	0.087	0.09		892	
	non noble metal	lead	7439-92-1	3.322	3.41	3.57	34057	35662
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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